PART NUMBER: BMD-200-EVAL Version 3.1
DESCRIPTION:
BMD-200 Evaluation Board PCB

Rigado LLC
2601 25th ST SE, STE 200
Salem, OR 97302

Approvals:

Drawn:	DCN	Date:	9/30/2014
Checked:			
Proj. Mgr.:			
Rlsd.:			

REVISIONS:

Rev	Date	Description of Change	Approval
3.0	8/15/2014	Initial eval with ATSAM3U	DCN
3.1	9/30/2014	Updated LTB parts, power ORing, jumper and silk cleanup	DCN

CAD PROGRAM / VERSION: Cadsoft Eagle / 6.6.0

PANEL DRAWING: N/A

SPECIFICATIONS (all referenced documentation refers to the latest rev):

APPLICABLE STANDARDS IPC-A-600 & IPC-6010 Series, Class 2	MATERIAL: FR-4 or better (SEE STACK-UP SHEET.)
NUMBER OF LAYERS: 4	SOLDERMASK: 2 SIDES COLOR: LOW GLOSS BLUE
LAYER ORDER: L01-L02-L03-L04	PLATING: ELECTROLESS NICKEL IMMERSION GOLD (ENIG) PER IPC-4552
SILKSCREEN: WHITE, TOP AND BOTTOM	ELECTRICAL TEST: Required
INTERNAL ROUTING: N/A	MINIMUM TRACE WIDTH: 0.006"
MINIMUM HOLE SIZE: 0.008"	SHORTED NETS:
MINIMUM SPACING: 0.006"	OTHER: Board Thickness = 0.062", 1oz Copper, 2.55"x 1.9", 173 holes
FLAMMABILITY: UL94V-0	

The following files have been archived under this part number:

SUPPLIER FILES: BMD-200_eval_3v1.ZIP			
FILENAME	**FILE CONTENTS**	**FILENAME**	**FILE CONTENTS**
BMD-200_eval.L1	COPPER LAYER 1	BMD-200_eval_ref_BOM_3v1.pdf	BILL OF MATERIALS
BMD-200_eval.L2	COPPER LAYER 2	BMD-200_eval.ipc	NETLIST
BMD-200_eval.L3	COPPER LAYER 3	BMD-200_eval_centroid.csv	PART PLACEMENT
BMD-200_eval.L4	COPPER LAYER 4	README.txt	INSTRUCTIONS
BMD-200_eval.top.stop	TOP SOLDERMASK		
BMD-200_eval.bot.stop	BOT SOLDERMASK		
BMD-200_eval.top.silk	TOP SILKSCREEN		
BMD-200_eval.bot.silk	BOT SILKSCREEN		
BMD-200_eval.top.stencil	TOP PASTE		
BMD-200_eval.bot.stencil	BOTTOM PASTE		
BMD-200_eval.drd	EXCELLON DRILL FILE		
BMD-200_eval.dri	DRILL INFO FILE		
BMD-200_eval.outline	BOARD OUTLINE FILE		
BMD-200_eval.CAD	FABMASTER FILE		
BMD-200_eval-fab.pdf	FAB DRAWING		
BMD-200_eval-assembly-top.pdf	TOP ASSEMBLY		
BMD-200-eval_cover_sheet_3v1.pdf	COVER SHEET		